



Material Content Data Sheet



Sales Product Name	TLE4699E			Issued	9. January 2019			
MA#	MA000970052							
Package	PG-SSOP-14-2			Weight*	83.45 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.837	3.40	3.40	33994	33994
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8257	
wire	non noble metal	copper	7440-50-8	27.978	33.53	34.41	335276	344049
	noble metal	gold	7440-57-5	0.154	0.18	0.18	1850	1850
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1163
encapsulation	plastics	epoxy resin	-	4.466	5.35		53515	
	inorganic material	silicondioxide	60676-86-0	43.977	52.70	58.17	527005	581683
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11698	11698
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9199	9199
glue	plastics	epoxy resin	-	0.366	0.44		4382	
	noble metal	silver	7440-22-4	1.097	1.31	1.75	13145	17527
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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